

TRIACS

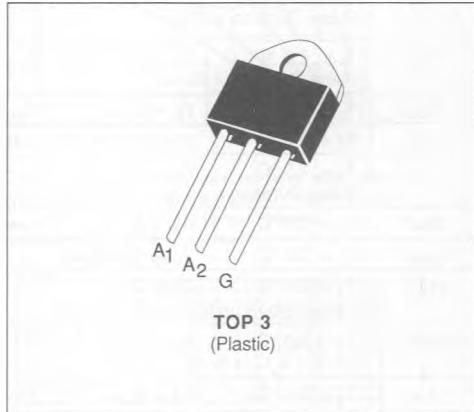
- GLASS PASSIVATED CHIP
- IGT SPECIFIED IN FOUR QUADRANTS

DESCRIPTION

This new design of plastic uninsulated power triacs offers maximum efficiency with maximum ease of mounting.

ADVANTAGES

- NO TAPPING REQUIRED FOR FIXING
- EXCELLENT THERMAL IMPEDANCE AND HIGH RELIABILITY CONSTRUCTION


ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
$I_{T(\text{RMS})}$	RMS on-state Current (360° conduction angle)	$T_C = 90^\circ\text{C}$	30	A
$I_{T\text{SM}}$	Non Repetitive Surge Peak on-state Current (T_j initial = 25 °C - Half sine wave)	$t = 8.3 \text{ ms}$	260	A
		$t = 10 \text{ ms}$	250	
I^2t	I^2t Value for Fusing	$t = 10 \text{ ms}$	312.5	A^2s
di/dt	Critical Rate of Rise of on-state Current (1)	Repetitive $F = 50 \text{ Hz}$	10	$\text{A}/\mu\text{s}$
		Non Repetitive	50	
T_{stg} T_j	Storage and Operating Junction Temperature Range	- 40 to 125 - 40 to 125		$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	BTB 26-					Unit
		200A	400A	600A	700A	800A	
V_{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1) $I_G = 1.5 \text{ A}$ $di/dt = 1 \text{ A}/\mu\text{s}$

(2) $T_j = 125^\circ\text{C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{\text{th} (\text{j}-\text{a})}$	Junction to Ambient	50	$^\circ\text{C}/\text{W}$
$R_{\text{th} (\text{c}-\text{h})}$	Contact (case-heatsink) with Grease	0.2	$^\circ\text{C}/\text{W}$
$R_{\text{th} (\text{j}-\text{c})}$ DC	Junction to Case for DC	1.2	$^\circ\text{C}/\text{W}$
$R_{\text{th} (\text{j}-\text{c})}$ AC	Junction to Case for 360 ° Conduction Angle ($F = 50 \text{ Hz}$)	0.9	$^\circ\text{C}/\text{W}$

GATE CHARACTERISTICS (maximum values)

$$P_{GM} = 40 \text{ W } (t_p = 10 \mu\text{s})$$

$$I_{GM} = 6 \text{ A } (t_p = 10 \mu\text{s})$$

$$P_G(AV) = 1 \text{ W}$$

$$V_{GM} = 16 \text{ V } (t_0 = 10 \mu\text{s})$$

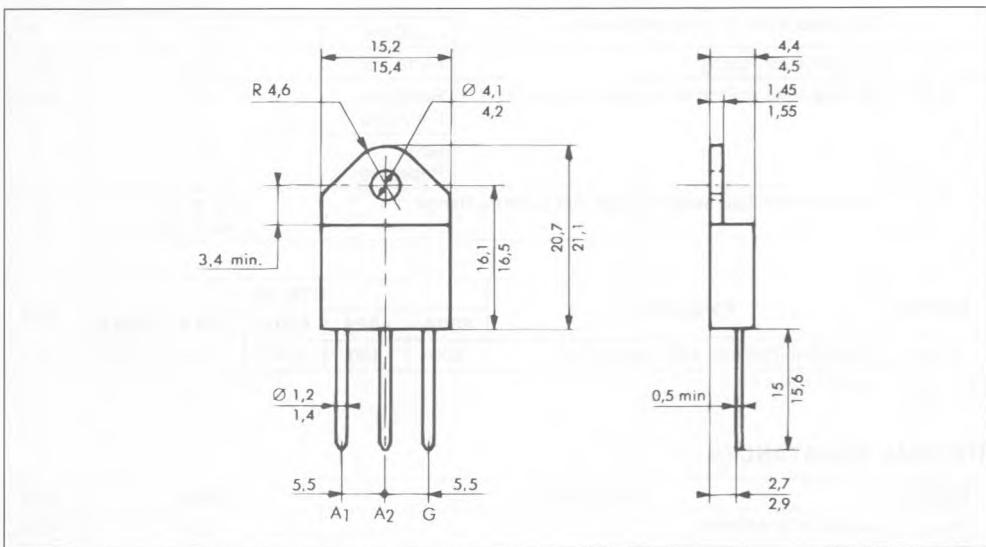
ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I_{GT}	$T_j = 25^\circ C$ $V_D = 12 V$ Pulse Duration > 20 μs			I-II-III	1		100	mA
				IV	1		150	
V_{GT}	$T_j = 25^\circ C$ Pulse Duration > 20 μs	$V_D = 12 V$	$R_L = 33 \Omega$	I-II-III-IV			1.5	V
V_{GD}	$T_j = 125^\circ C$	$V_D = V_{DRM}$	$R_L = 3.3 k\Omega$	I-II-III-IV				V
I_H^*	$T_j = 25^\circ C$	$I_T = 500 mA$	Gate Open			30	100	mA
I_L	$T_j = 25^\circ C$ Pulse Duration > 20 μs	$V_D = 12 V$	$I_G = 300 mA$	I-II-III-IV			150	mA
V_{TM}^*	$T_j = 25^\circ C$	$I_{TM} = 35 A$	$t_p = 10 ms$				1.7	V
I_{DRM}^*	$T_j = 125^\circ C$	V_{DRM} Specified				1.5	6	mA
dV/dt^*	$T_j = 125^\circ C$ Linear Slope up to $V_D = 67 \% V_{DRM}$	Gate Open			250			V/ μs
$(dV/dt)_c^*$	$T_C = 90^\circ C$ $(di/dt)_c = 13.3 A/ms$	$V_D = V_{DRM}$	$I_T = 35 A$		10			V/ μs
t_{g1}	$T_j = 25^\circ C$ $I_G = 1 A$	$V_D = V_{DRM}$	$I_T = 35 A$ $di/dt = 10 A/\mu s$	I-II-III-IV		2.5		μs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

PACKAGE MECHANICAL DATA

TOP 3 Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 5 g

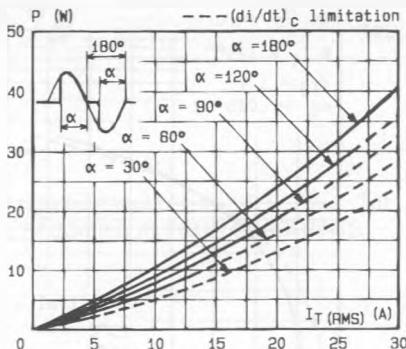


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

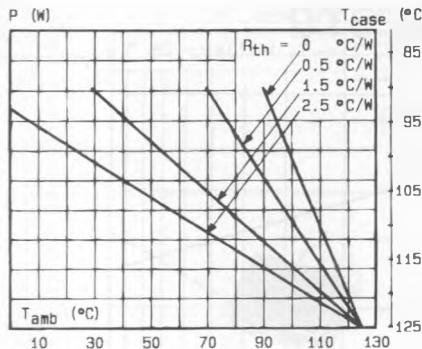


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

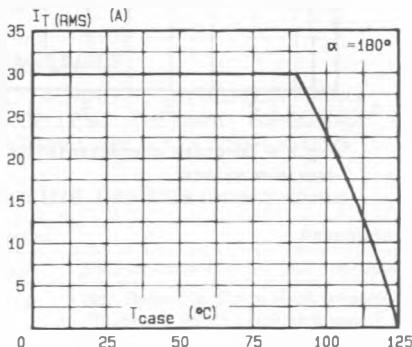


Fig.3 - RMS on-state current versus case temperature.

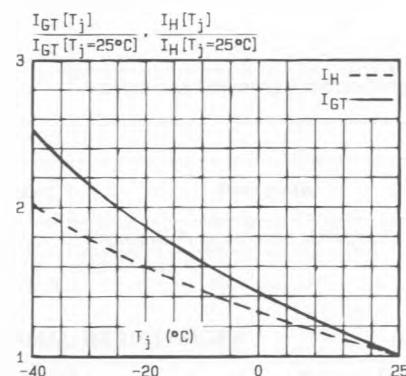


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

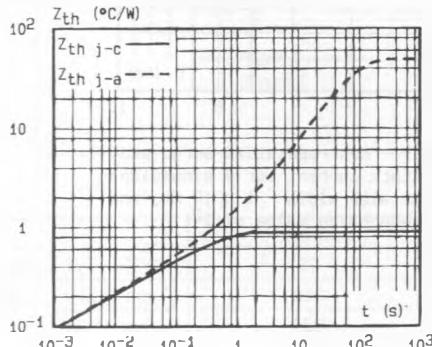


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

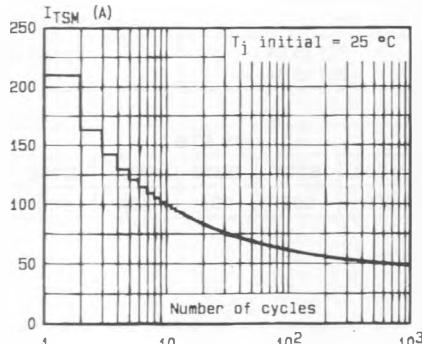


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

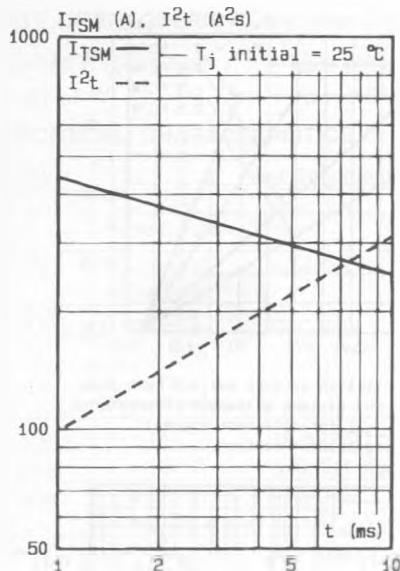


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms. and corresponding value of I^2t .

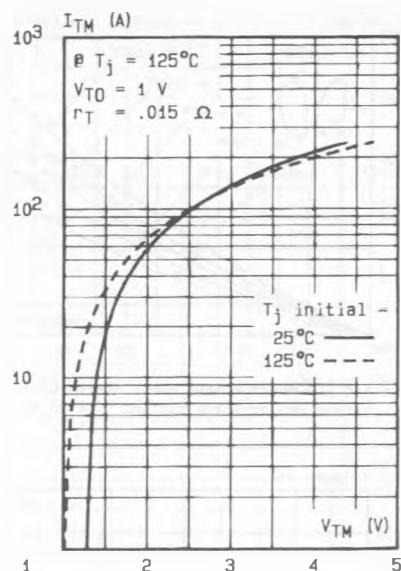


Fig.8 - On-state characteristics (maximum values).